

P25N

Polyimide-based No Flow Prepreg

Isola offers a P25N product line of polyimide-based no flow prepreg materials for high temperature printed circuit applications.

These products consist of a polyimide resin system suitable for military, commercial or industrial electronic applications requiring superior performance and the utmost in thermal properties. These products utilize a polyimide and thermoplastic blend resin, fully cured without the use of Methylenedianiline (MDA). This results in a polymer with a high Tg without the characteristic difficulties of brittleness and low initial bond strength associated with traditional thermoset polyimides.

Product Attributes

Halogen Free, No / Low Flow Prepreg, Polyimide

Typical Market Applications

Aerospace & Defense , Consumer Electronics , Medical, Industrial & Instrumentation

ORDERING INFORMATION:

Contact your local sales representative or visit www.isola-group.com for further information.

Isola Group 3100 West Ray Road

Suite 301

Chandler, AZ 85226

Phone: 480-893-

Fax: 480-893-1409 info@isola-

group.com

Isola Asia Pacific (Hong Kong)

Ltd.

Unit 3512 - 3522, 35/F No. 1 Hung To Road, Kwun

Tong,

Kowloon, Hong Kong Phone: 852-2418-1318 Fax: 852-2418-1533

info.hkg@isola-group.com

Isola GmbH

Isola Strasse 2 D-52348 Düren,

Germany

Phone: 49-2421-8080 Fax: 49-2421-808164 info-dur@isola-

group.com

Halogen Free

Data Sheet

Tg 250°C Td 383°C Dk 3.67 Df 0.0187

IPC-4101 - / 42

UL - File Number E41625

Last Updated July 15, 2019 Revision No: B

Product Features

- · Industry Recognition
 - UL File Number: E41625
 - RoHS Compliant
- · Performance Attributes
 - Halogen free
- · Processing Advantages

Product Availability

- · Standard Material Offering: Laminate
- · Copper Foil Type
- · Copper Weight
- · Standard Material Offering: Prepreg
 - Roll or panel form
 - Tooling of prepreg panels
- · Glass Fabric Availability
 - E-glass

Property		Typical Value	Units	Test Method
			Metric (English)	IPC-TM-650 (or as noted)
Glass Transition Temperature (Tg) by DSC		250	°C	2.4.25C
Decomposition Temperature (Td) by TGA @ 5% weight loss		383	°C	2.4.24.6
Time to Delaminate by TMA (Copper removed)	A. T260 B. T288	60	Minutes	2.4.24.1
Z-Axis CTE	A. Pre-Tg B. Post-Tg C. 50 to 260°C, (Total Expansion)	55 TBD 	ppm/°C ppm/°C %	2.4.24C
X/Y-Axis CTE	Pre-Tg	13/14	ppm/°C	2.4.24C
Thermal Conductivity		0.4	W/mK	ASTM E1952
Thermal Stress 10 sec @ 288ºC (550.4ºF)	A. Unetched B. Etched	Pass	Pass Visual	2.4.13.1
Dk, Permittivity	A. @ 100 MHz B. @ 500 MHz C. @ 1 GHz D. @ 2 GHz	3.75 3.72 3.70 3.67	_	2.5.5.9 2.5.5.9 2.5.5.9 Bereskin Stripline
Df, Loss Tangent	A. @ 100 MHz B. @ 500 MHz C. @ 1 GHz D. @ 2 GHz	0.0140 0.0157 0.0180 0.0198	_	2.5.5.9 2.5.5.9 2.5.5.9 Bereskin Stripline
Volume Resistivity	A. After moisture resistance B. At elevated temperature	3.0 x 10 ⁸ 7.0 x 10 ⁸	MΩ-cm	2.5.17.1
Surface Resistivity	A. After moisture resistance B. At elevated temperature	3.0 x 10 ⁶ 2.0 x 10 ⁸	ΜΩ	2.5.17.1
Dielectric Breakdown		>55	kV	2.5.6B
Arc Resistance		130	Seconds	2.5.1B
Electric Strength (Laminate & laminated prepreg)		44 (1100)	kV/mm (V/mil)	2.5.6.2A
Comparative Tracking Index (CTI)		4 (100-174)	Class (Volts)	UL 746A ASTM D3638
Flexural Strength	A. Length direction B. Cross direction	83.6 55.5	ksi	2.4.4B
Tensile Strength	A. Length direction B. Cross direction	55.0 35.4	ksi	ASTM D3039
Moisture Absorption		0.5	%	2.6.2.1A
Flammability (Laminate & laminated prepreg)		НВ	Rating	UL 94
Max Operating Temperature		140	°C	UL 796

The data, while believed to be accurate and based on analytical methods considered to be reliable, is for information purposes only. Any sales of these products will be governed by the terms and conditions of the agreement under which they are sold.



NOTE

Visit our site http://www.isola-group.com for more details. Revision B: Corrected units for Flexural and Tensile Strength